

Title (en)

Electrolytic deposition of gold-containing alloys.

Title (de)

Elektroplattierung von Gold enthaltenden Legierungen.

Title (fr)

Dépôt électrolytique d'alliages d'or.

Publication

EP 0384679 B1 19940817 (EN)

Application

EP 90301749 A 19900219

Priority

GB 8903818 A 19890220

Abstract (en)

[origin: EP0384679A1] A gold-copper alloy of good corrosion resistance is electrolytically deposited from a bath containing a cyanide compound of gold (e.g. $\text{KAu}(\text{CN})_2$), a cyanide compound of copper and tellurium or bismuth in the form of a soluble salt (e.g. sodium tellurite), the bath being substantially free of any other metal in an electrolytically depositable form. The bath generally also contains a cyanide salt (e.g. KCN) and may also contain a surface-active agent. Foreign metals, e.g. zinc, may be chelated or complexed to prevent deposition thereof.

IPC 1-7

C25D 3/62

IPC 8 full level

C25D 3/62 (2006.01)

CPC (source: EP)

C25D 3/62 (2013.01)

Cited by

EP2604727A1; IT201900001769A1; DE102011056318B3; WO2009037180A1; US9567684B2; US9683303B2; US10233555B2; US10619260B2; WO2020160951A1; EP1983077B1

Designated contracting state (EPC)

AT BE CH DE DK ES FR GB GR IT LI LU NL SE

DOCDB simple family (publication)

EP 0384679 A1 19900829; EP 0384679 B1 19940817; AT E110124 T1 19940915; DE 69011549 D1 19940922; DE 69011549 T2 19950406; GB 8903818 D0 19890405

DOCDB simple family (application)

EP 90301749 A 19900219; AT 90301749 T 19900219; DE 69011549 T 19900219; GB 8903818 A 19890220